Chip Scale Review®

ChipScaleReview.com

The Future of Semiconductor Packaging

2018 Editorial Calendar

July • August

(Editorial close date: 6/15) — * indicates show distribution

Topics	Shows
High reliability materials Metal-based wafer-level and 3D printed packaging Temporary bonding for high temperature processing of thin glass Chip-package-board co-design Coaxial socket technology Testing RF devices Large-area fan-out processing	• **ICEPT 2018** Shanghai, China (Aug 8-11) • **SEMICON Taiwan *** Taipei, Taiwan (Sept 5-7) • **European MEMS & Sensors Summit** Grenoble, France (Sept 19-21) • **European Imaging & Sensors Summit** Grenoble, France (Sept 19-21) • **Strategic Materials Conference - SMC** San Jose, CA (Sept 24-26)

International Directory of Wafer Probers & Probe Cards

Ad Space Close Jun 30 - Ad Materials Close Jul 7

September • October

(Editorial close date: (7/20)) — * indicates show distribution

Topics	Shows
Effective, Scalable EMI Protection Embedded RDL High density flip-chip and advanced CSP High-resolution 3D X-ray metrology Advanced substrates and embedded packaging High density advanced packaging (HDAP) design Direct-placement process for LED's Inspection strategies High density advanced packaging design	•**SMTA International *** Rosemont, IL (October 14-18) • **IWLPC-International Wafer-Level Packaging Conference & Exhibition *** San Jose, CA (Oct 23-25) • **TestConX China 2018** Suzhou, China (Oct 23) Shenzhen, China (Oct 25) • **MEMS & Sensors Executive Congress** Napa, CA (Oct 28-30) • **International Test Conference (ITC)** Phoenix, AZ (Oct 31- Nov 2) • **SEMI International Technology Partners Conference (ITPC)** Maui, Hawaii (Nov 4-7) • **SEMICON Europa** Munich, Germany (Nov 13-16)

International Directory of Defect Inspection Systems

Ad Space Close Sep 8 - Ad Materials Close Sep 15

November • December

(Editorial close date: 9/21) — * indicates show distribution

Topics	Shows
5G developments Cooling solutions for hi-density chips Burn-in system technology advancements Advanced eWLB for mmWave applications Package assembly design kits Collective bonding for heterogeneous integration Lithography Photonics for next generation applications Robust interconnects for MEMS sensors Wafer bumping	• **EPTC 2018 *** Singapore (Dec 4-7) • **MEPTEC: Heterogeneous Integration Symposium** Milpitas, CA (Dec 5) • **SEMICON Japan** Tokyo, Japan (Dec 12-14) • **SEMI European 3D Summit *** Dresden, Germany (Jan 22-24, 2019) • **SEMICON Korea** Coex, Seoul, Korea (Jan 23-25, 2019)

Ad Space Close Nov 3 - Materials Close Nov 10

For ad inquiries: ads@chipscalereview.com - For editorial inquiries editor@chipscalereview.com

Notes: Editorial calendar topics and distribution are subject to change without notice and are contingent on logistics and magazine production.

Haley Publishing Inc.2018 All rights reserved. Rev:CSR-EC-090718